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FDS4559

60V Complementary PowerTrench®MOSFET

General Description

This complementary MOSFET device is produced using ON Semiconductor's advanced PowerTrench process that has been especially tailored to minimize the on-state resistance and yet maintain low gate charge for superior switching performance.

Applications

- DC/DC converter
- · Power management
- · LCD backlight inverter

Features

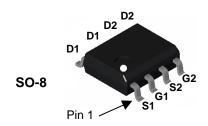
Q1: N-Channel

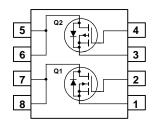
4.5 A, 60 V
$$R_{DS(on)} = 55 \ m\Omega \ @ \ V_{GS} = 10V$$

$$R_{DS(on)} = 75 \ m\Omega \ @ \ V_{GS} = 4.5V$$

Q2: P-Channel

$$-3.5$$
 A, -60 V $\rm~R_{DS(on)}=105~m\Omega$ @ V $_{GS}=-10$ V
$$\rm~R_{DS(on)}=135~m\Omega$$
 @ V $_{GS}=-4.5$ V





Absolute Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter		Q1	Q2	Units
V _{DSS}	Drain-Source Voltage		60	-60	V
V _{GSS}	Gate-Source Voltage		±20	±20	V
I _D	Drain Current - Continuous	(Note 1a)	4.5	-3.5	Α
	- Pulsed		20	-20	
P _D	Power Dissipation for Dual Operation		2	2	W
	Power Dissipation for Single Operation	(Note 1a)	1.	6	
		(Note 1b)	1.	2	
		(Note 1c)	1		
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to	+175	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	78	°C/W
R _{θJC}	Thermal Resistance, Junction-to-Case	(Note 1)	40	°C/W

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
FDS4559	FDS4559	13"	12mm	2500 units

Symbol	Parameter	Test Conditions	Type	Min	Тур	Max	Units
Drain-So	ource Avalanche Rating	QS (Note 1)					
W _{DSS}	Single Pulse Drain-Source Avalanche Energy	$V_{DD} = 30 \text{ V}, \qquad I_{D} = 4.5 \text{ A}$	Q1			90	mJ
I _{AR}	Maximum Drain-Source Avalanche Current		Q1			4.5	Α
Off Chai	racteristics						
BV _{DSS}	Drain-Source Breakdown	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	Q1	60			V
. D) /	Voltage	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	Q2	-60			11/06
ΔBV _{DSS}	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, Referenced to 25°C	Q1 Q2		58 –49		mV/°(
ΔT_J I_{DSS}	Zero Gate Voltage Drain	$I_D = -250 \mu A$, Referenced to 25°C $V_{DS} = 48 \text{ V}$, $V_{GS} = 0 \text{ V}$	Q1		73	1	μА
IDSS	Current		Q2			_1 _1	μΑ
I _{GSS}	Gate-Body Leakage	$V_{DS} = -48 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	Q1			<u>+</u> 100	nA
000		$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	Q2			<u>+</u> 100	
On Char	racteristics (Note 2)						
	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	Q1	1	2.2	3	V
V GS(III)	Cate Theorica Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$ $V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	Q2	-1	-1.6	-3	•
$\Delta V_{GS(th)}$	Gate Threshold Voltage	I _D = 250 μA, Referenced to 25°C	Q1		-5.5		mV/°(
	Temperature Coefficient	$I_D = -250 \mu A$, Referenced to 25°C	Q2		4		
R _{DS(on)}	Static Drain-Source	$V_{GS} = 10 \text{ V}, I_D = 4.5 \text{ A}$	Q1		42	55	mΩ
	On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 4.5 \text{ A}, T_J = 125^{\circ}\text{C}$			72	94	
		$V_{GS} = 4.5 \text{ V}, I_D = 4 \text{ A}$ $V_{GS} = -10 \text{ V}, I_D = -3.5 \text{ A}$			55	75	_
			Q2		82	105	
		$V_{GS} = -10 \text{ V}, I_D = -3.5 \text{ A}, T_J = 125^{\circ}\text{C}$			130	190	
	On Otata Basin Oneman	$V_{GS} = -4.5 \text{ V}, I_D = -3.1 \text{ A}$	04		105	135	
I _{D(on)}	On-State Drain Current	$V_{GS} = 10 \text{ V}, V_{DS} = 5 \text{ V}$	Q1 Q2	20 –20			Α
g _{FS}	Forward Transconductance	$V_{GS} = -10 \text{ V}, V_{DS} = -5 \text{ V}$ $V_{DS} = 10 \text{ V}, I_{D} = 4.5 \text{ A}$	Q1	20	14		S
91-2	Torrara Transconadoranco	$V_{DS} = -5 \text{ V}, I_D = -3.5 \text{ A}$	Q2		9		
Dynami	c Characteristics					•	1
	Input Capacitance	Q1	Q1		650		pF
Ciss	при Сараспансе	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$	Q2		759		ρι
Coss	Output Capacitance	f = 1.0 MHz	Q1		80		pF
- 033		Q2	Q2		90		
Crss	Reverse Transfer	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V},$	Q1		35		pF
	Capacitance	f = 1.0 MHz	Q2		39		
N ! 4 a la ! a	u Obanastaniatiaa						
	Characteristics (Note 2		04		1 44	00	
I(on)	urn-On Delay Time	Q1 $V_{DD} = 30 \text{ V}, I_{D} = 1 \text{ A},$	Q1 Q2		11 7	20 14	ns
Т	urn-On Rise Time	$V_{\text{DD}} = 30 \text{ V}, I_{\text{D}} = 1 \text{ A},$ $V_{\text{GS}} = 10 \text{V}, R_{\text{GEN}} = 6 \Omega$	Q2 Q1		8	18	ns
'	dir Orraise Time	VGS = 10 V, 11GEN = 0 22	Q2		10	20	113
I(off)	urn-Off Delay Time	Q2	Q1		19	35	ns
.(=)	•	$V_{DD} = -30 \text{ V}, I_{D} = -1 \text{ A},$	Q2		19	34	
T	urn-Off Fall Time	$V_{GS} = -10 \text{ V}, R_{GEN} = 6 \Omega$	Q1		6	15	ns
_			Q2		12	22	
l _g T	otal Gate Charge	Q1	Q1		12.5	18	nC
\ \	Pata Sauraa Charaa	$V_{DS} = 30 \text{ V}, I_{D} = 4.5 \text{ A}, V_{GS} = 10 \text{ V}$	Q2		15	21	20
l _{gs}	Gate-Source Charge	Q2	Q1 Q2		2.4 2.5		nC
O _{gd}	Sate-Drain Charge	$V_{DS} = -30 \text{ V}, I_{D} = -3.5 \text{ A}, V_{GS} = -10 \text{ V}$	Q2 Q1		2.6		nC
·yu	Jan Brain Griango	, , , , , , , , , , , , , , , , , , , ,	Q2		3.0		

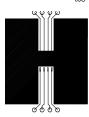
Electrical Characteristics (continued) $T_A = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Туре	Min	Тур	Max	Units
Drain-So							

Is	Maximum Continuous Drain-Source Diode Forward Current		Q1		1.3	Α
			Q2		-1.3	
V _{SD}	Drain-Source Diode Forward	$V_{GS} = 0 \text{ V}, I_S = 1.3 \text{ A} \text{ (Note 2)}$	Q1	0.8	1.2	V
	Voltage	$V_{GS} = 0 \text{ V}, I_{S} = -1.3 \text{ A}$ (Note 2)	Q2	-0.8	-1.2	

Notes

1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) 78°C/W when mounted on a 0.5 in² pad of 2 oz copper



b) 125°C/W when mounted on a .02 in² pad of 2 oz copper



c) 135°C/W when mounted on a minimum pad.

Scale 1:1 on letter size paper

2. Pulse Test: Pulse Width < 300μ s, Duty Cycle < 2.0%

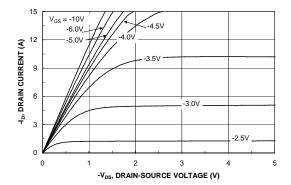


Figure 1. On-Region Characteristics.

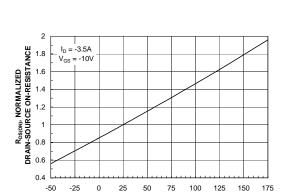


Figure 3. On-Resistance Variation with Temperature.

T_J, JUNCTION TEMPERATURE (°C)

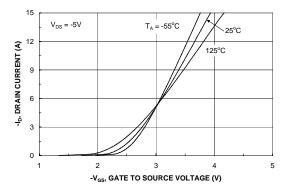


Figure 5. Transfer Characteristics.

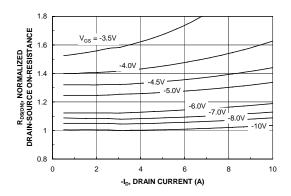


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

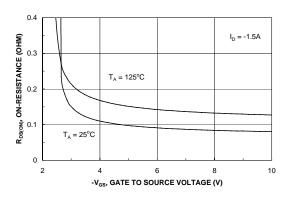


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

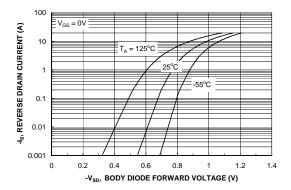


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

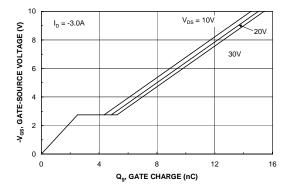


Figure 7. Gate Charge Characteristics.

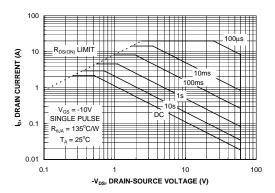


Figure 9. Maximum Safe Operating Area.

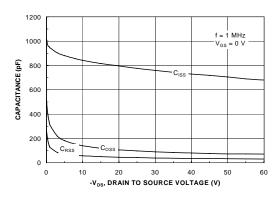


Figure 8. Capacitance Characteristics.

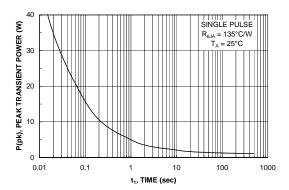


Figure 10. Single Pulse Maximum Power Dissipation.

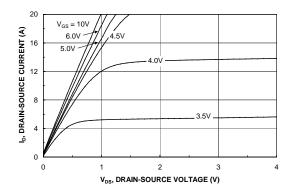


Figure 11. On-Region Characteristics.

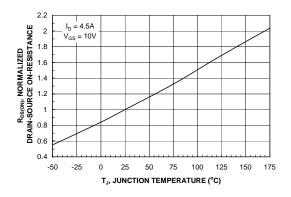


Figure 13. On-Resistance Variation with Temperature.

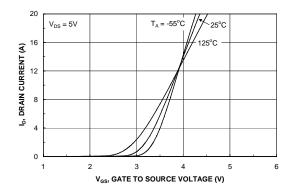


Figure 15. Transfer Characteristics.

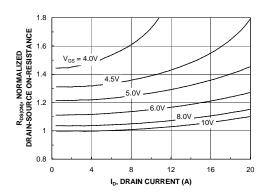


Figure 12. On-Resistance Variation with Drain Current and Gate Voltage.

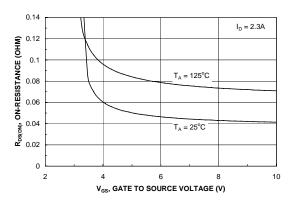


Figure 14. On-Resistance Variation with Gate-to-Source Voltage.

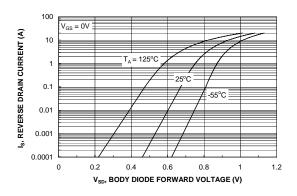
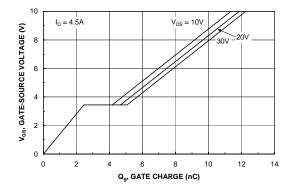


Figure 16. Body Diode Forward Voltage Variation with Source Current and Temperature.



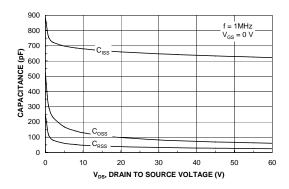
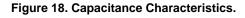
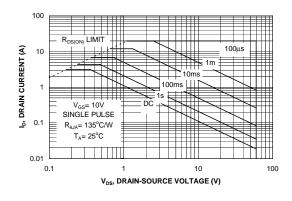


Figure 17. Gate Charge Characteristics.





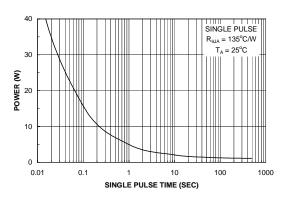


Figure 19. Maximum Safe Operating Area.

Figure 20. Single Pulse Maximum Power Dissipation.

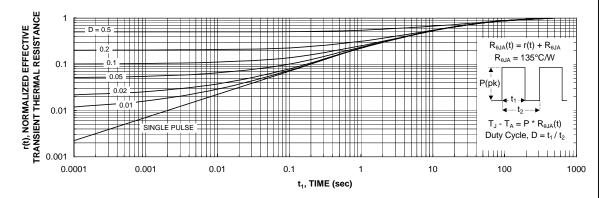


Figure 21. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c.

Transient thermal response will change depending on the circuit board design.

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